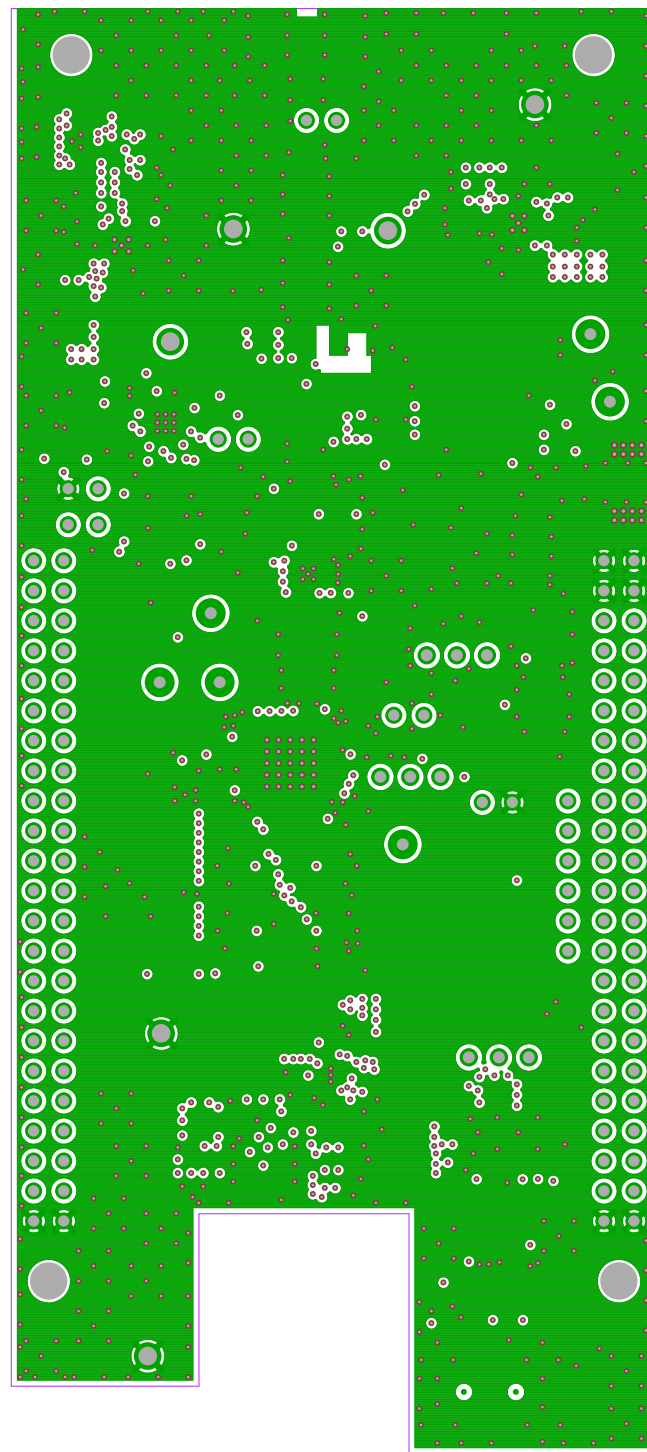
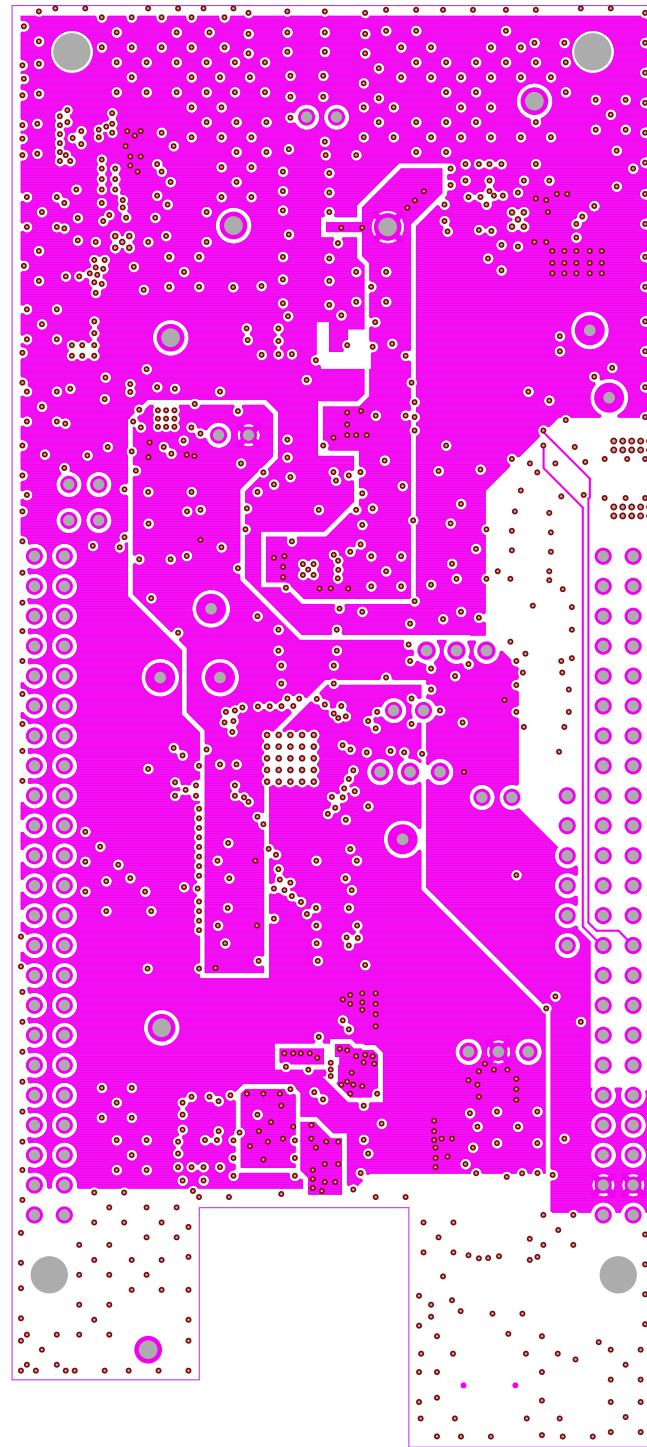


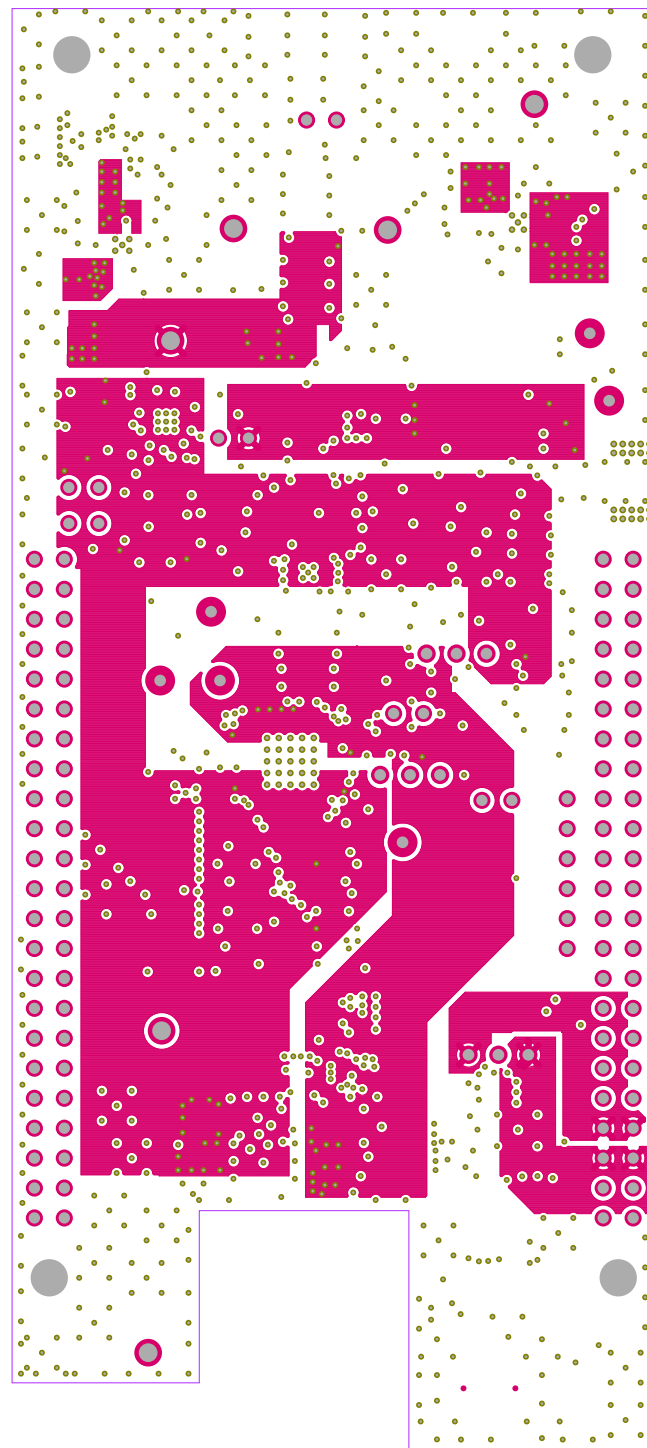
ADS41XX_CAPE REV E1
TIDA-00942
TOP SIDE



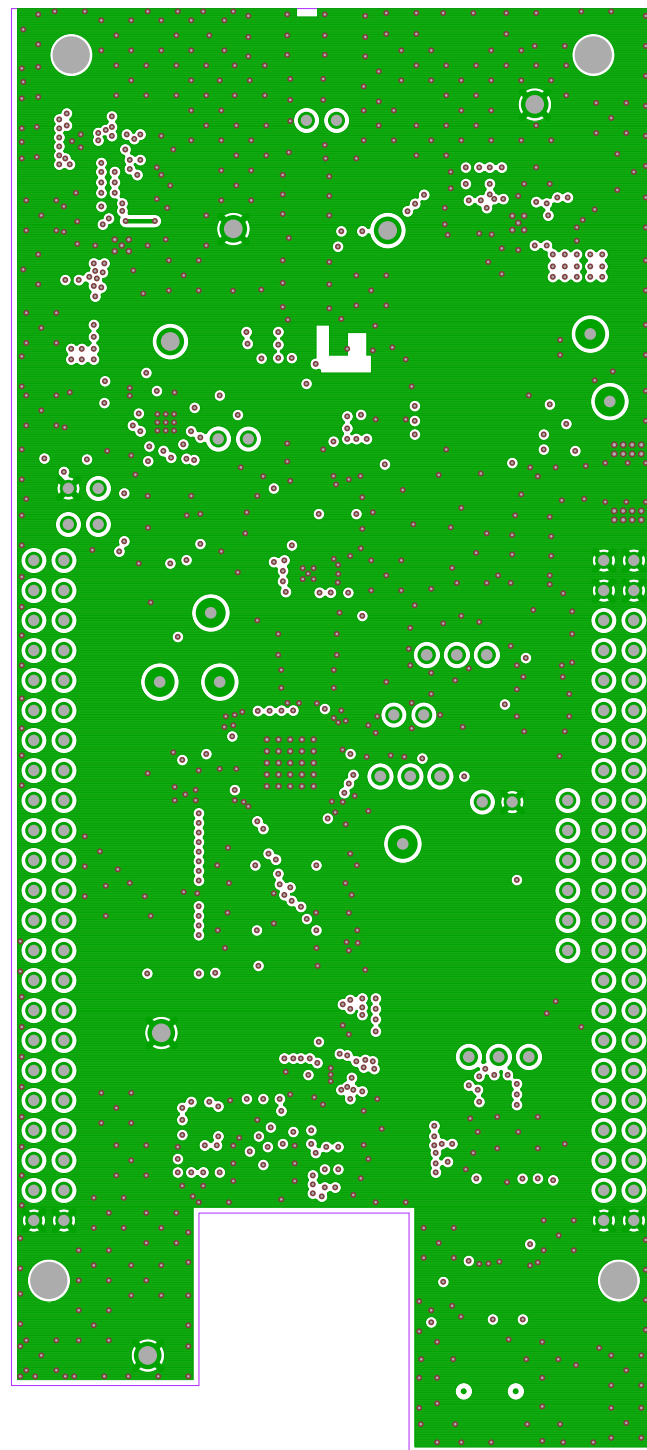
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TIDA-00942
GROUND PLANE 1



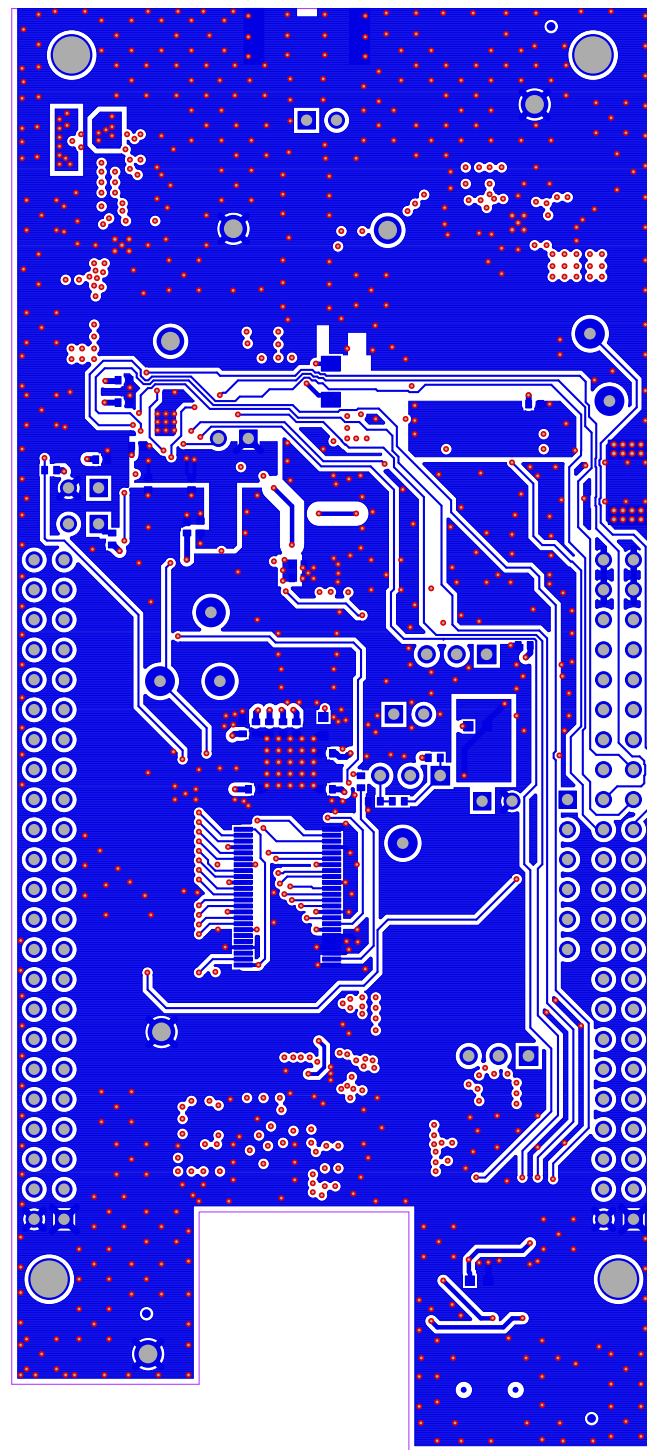
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TIDA-00942
POWER PLANE 1



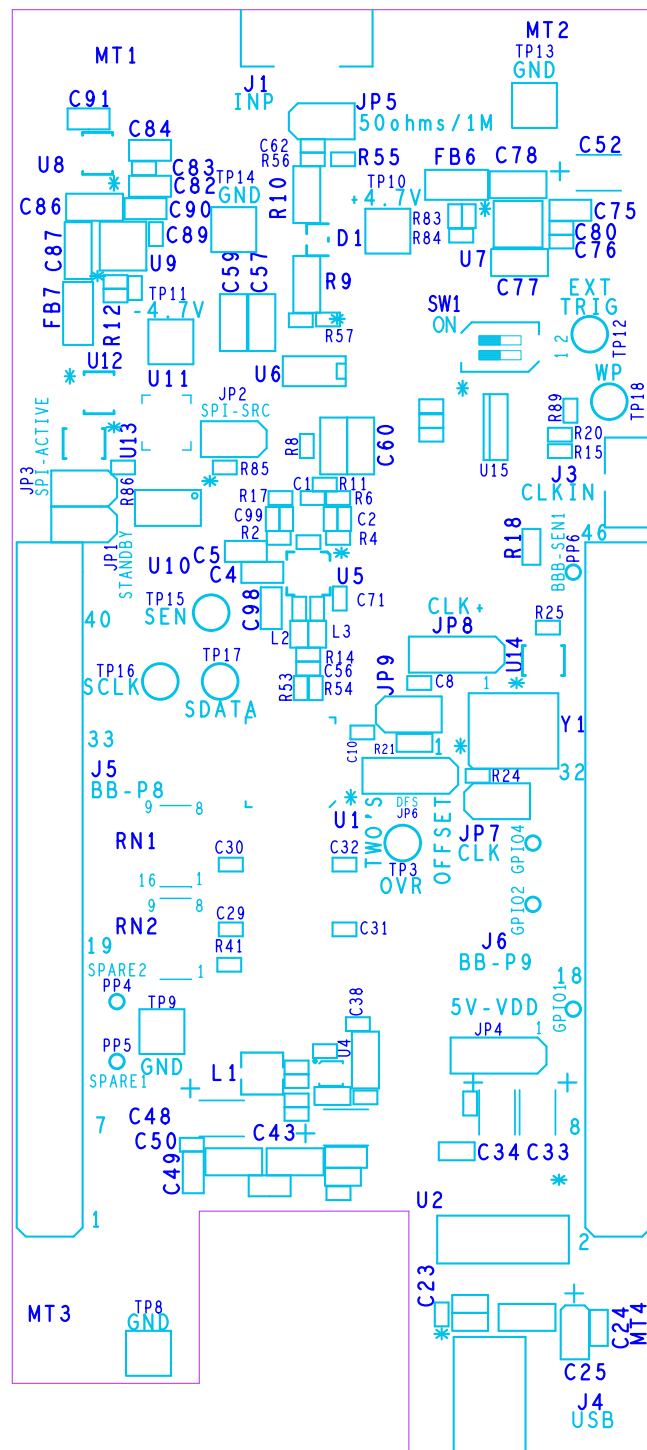
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TIDA-00942
POWER PLANE 2



ADS41XX_CAPE REV E1
TIDA-00942
GROUND PLANE 2



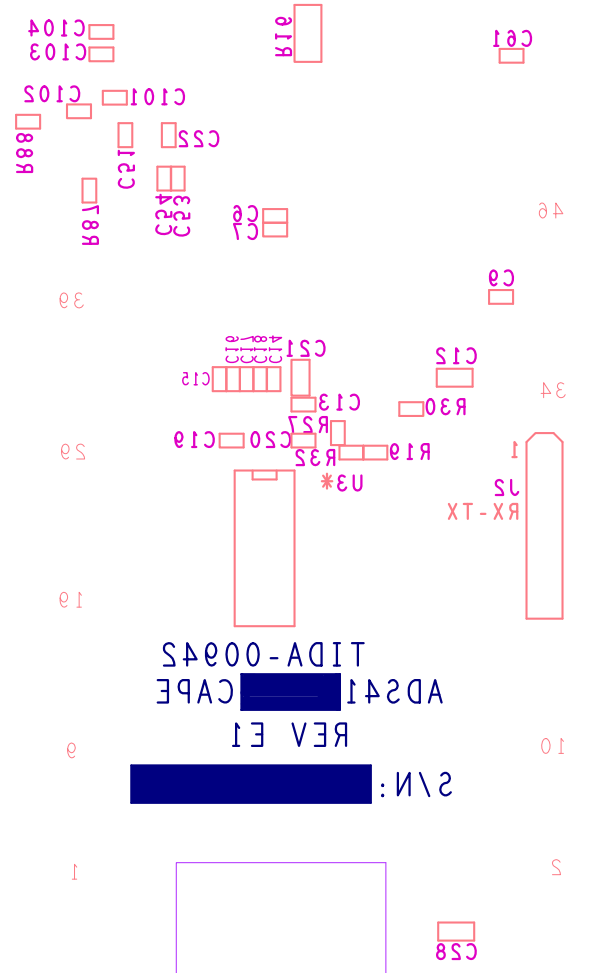
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TIDA-00942
BOTTOM SIDE



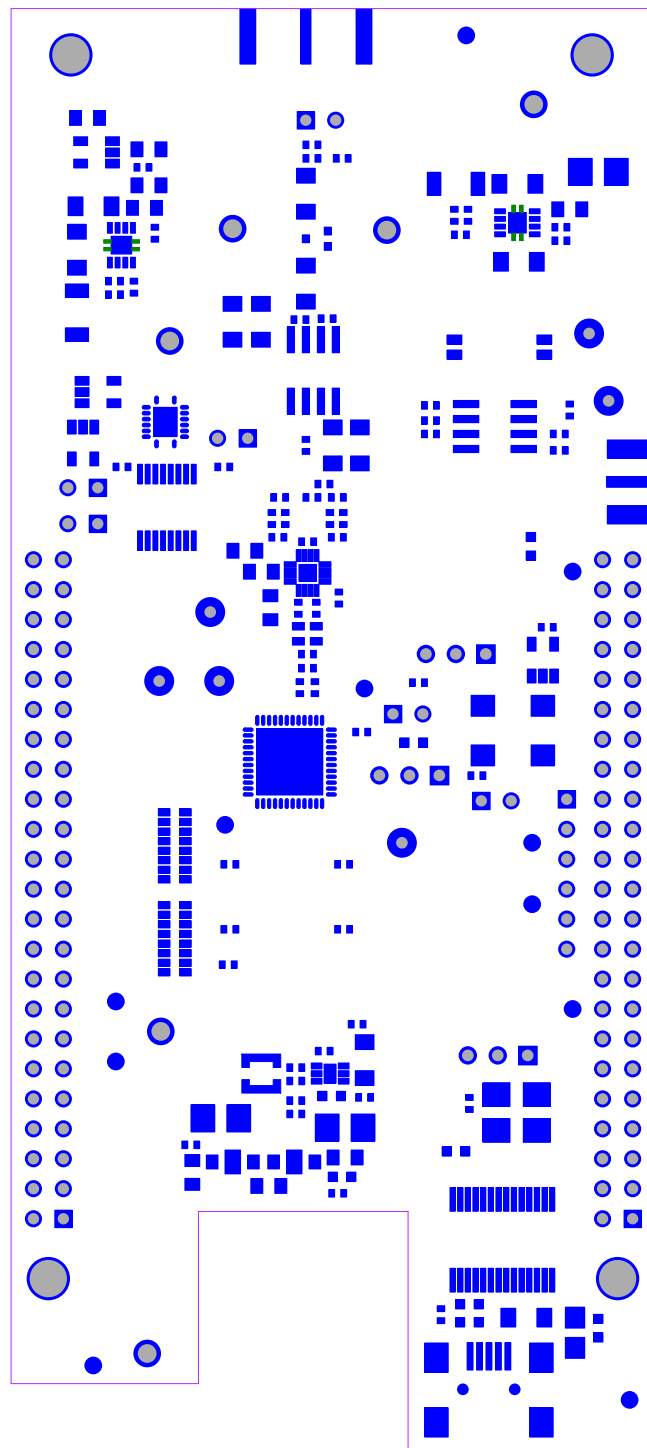
ADS41XX_CAPE REV E1
TIDA-00942
SILKSCREEN TOP



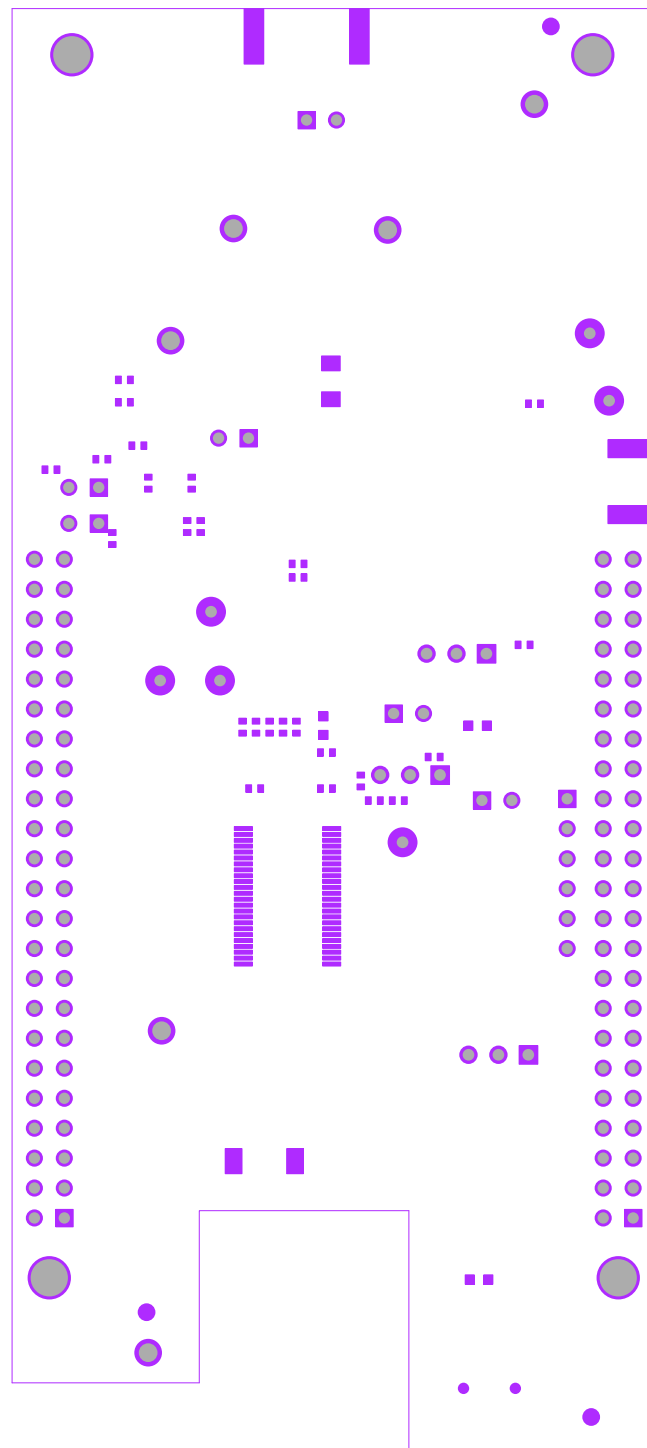
For evaluation only.
not FCC approved for resale.



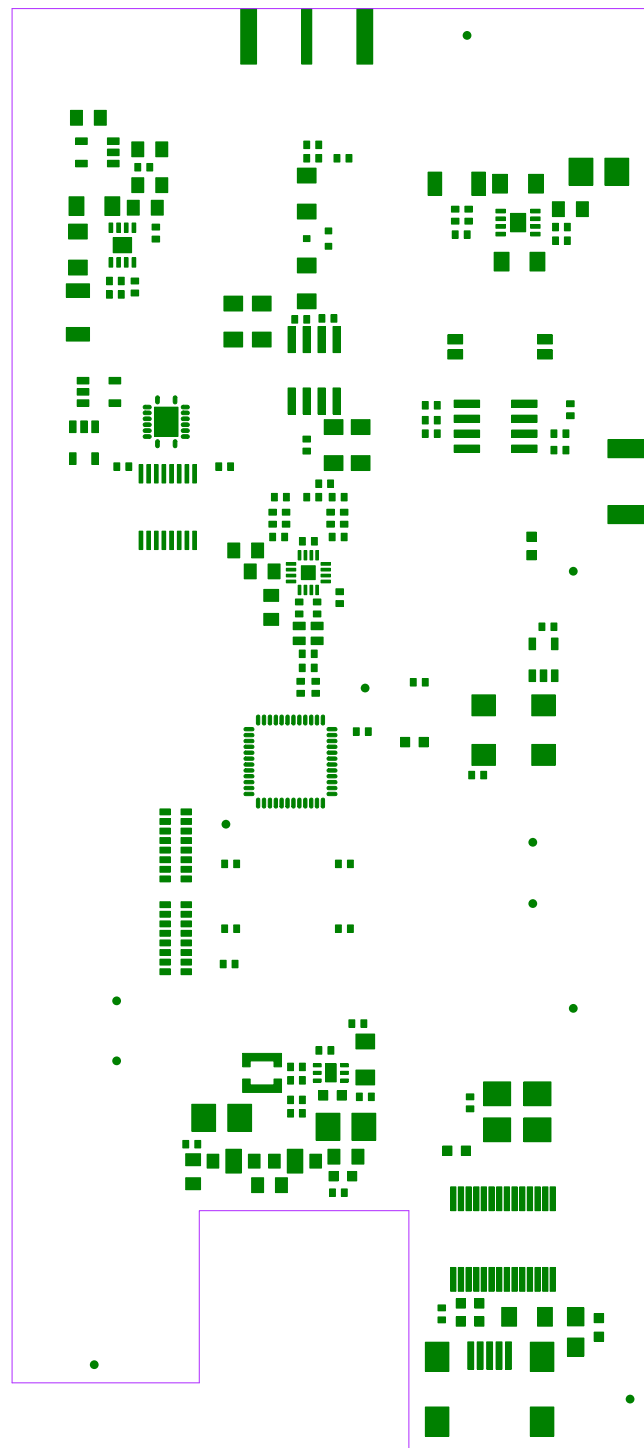
S/N: [REDACTED]
REV E1
AD241 [REDACTED] CAPE
TIDA-0042



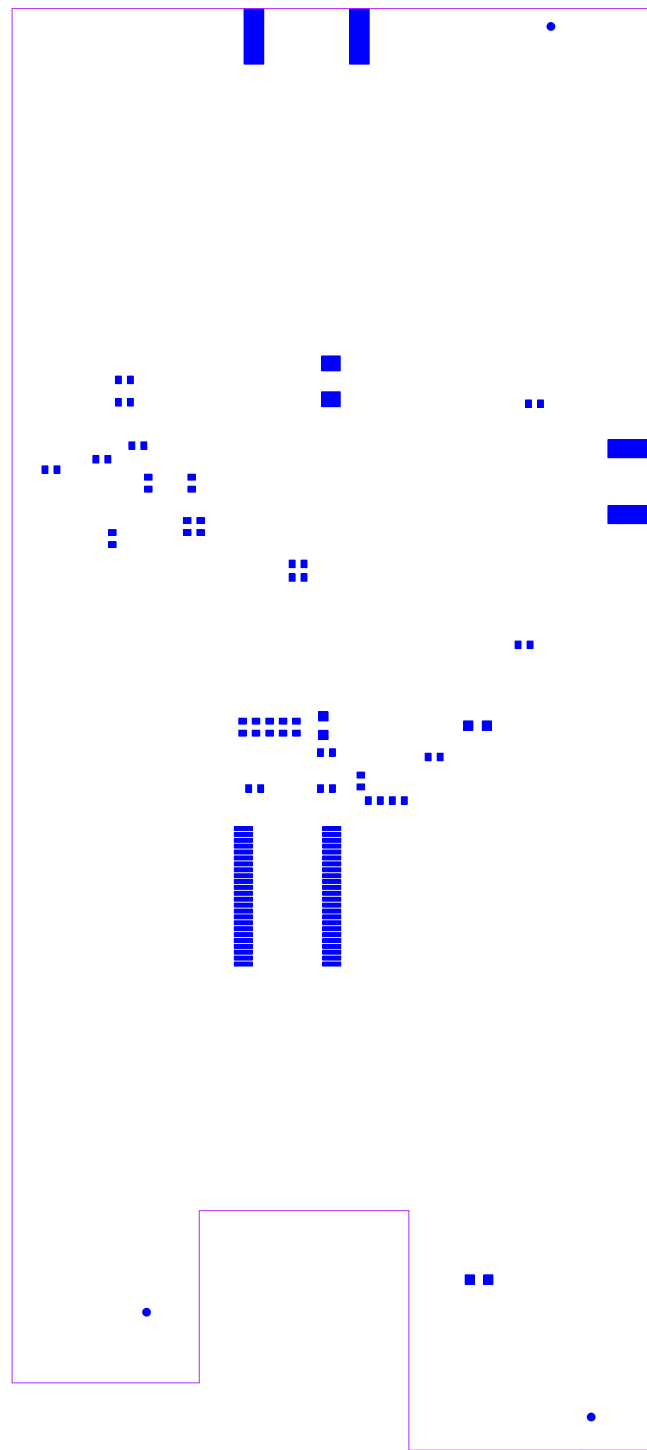
ADS41XX_CAPE REV E1
TIDA-00942
SOLDERMASK TOP



ADS41XX_CAPE REV E1
TIDA-00942
SOLDERMASK BOTTOM



ADS41XX_CAPE REV E1
TIDA-00942
PASTEMASK TOP



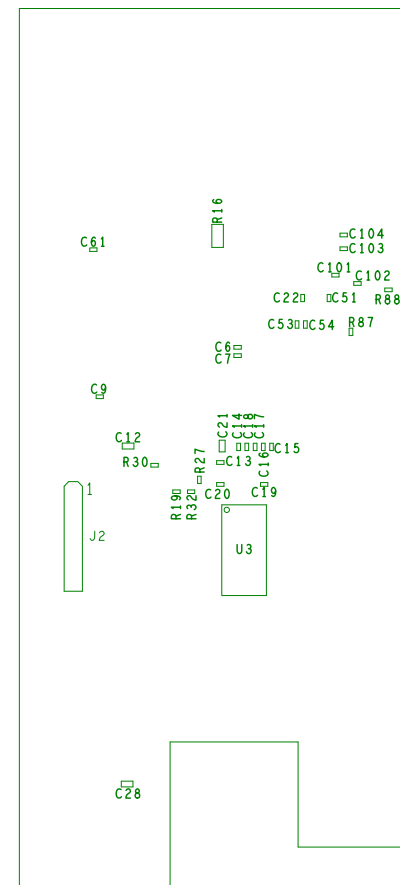
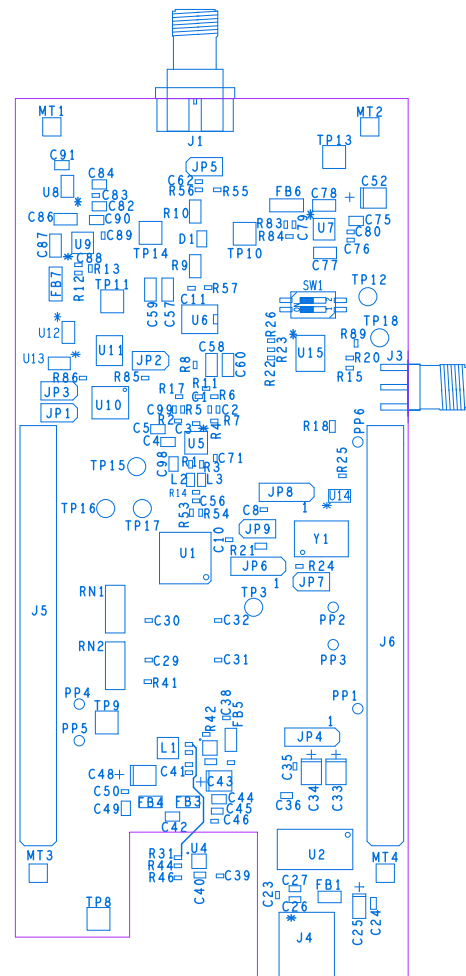
ADS41XX_CAPE REV E1
TIDA-00942
PASTEMASK BOTTOM

THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN

1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. FINISHED ASSEMBLY MUST BE RoHS COMPLIANT AND LEAD FREE.
3. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY.
4. DO NOT TRIM THE LEADS OF J2, J5 AND J6.

REVISIONS

REV	DESCRIPTION	DATE	APPROVED

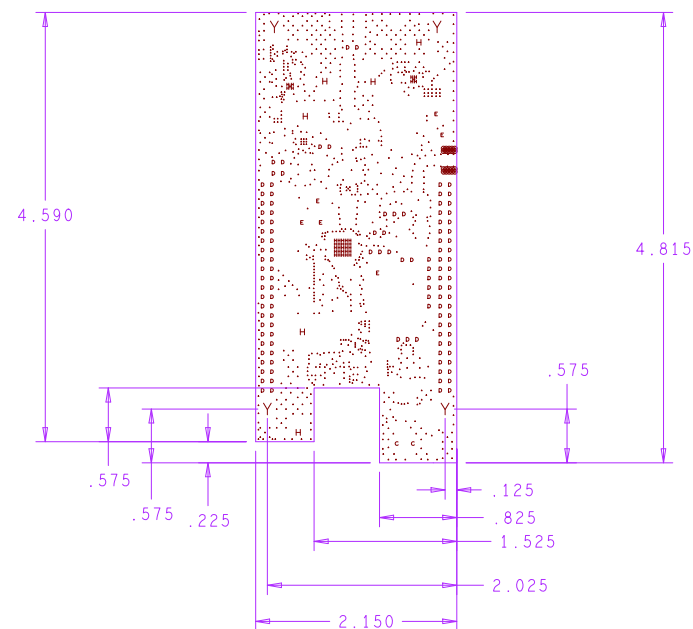
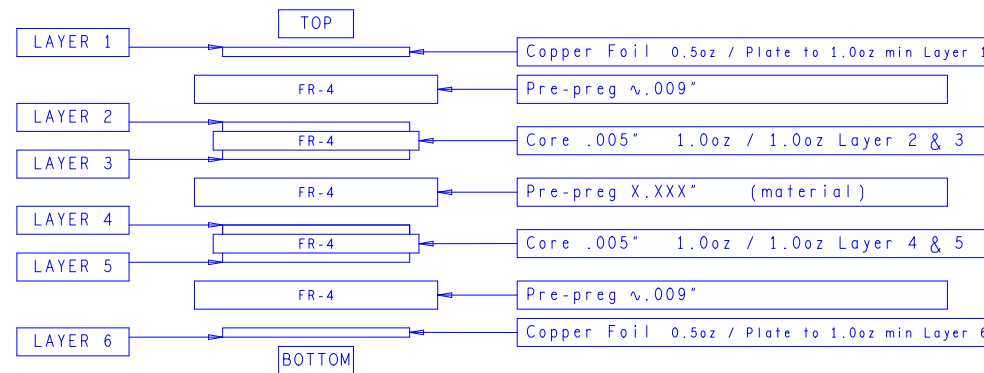


UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS:
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012 / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, CLASS 2, CURRENT REVISION.
IPC-A-600 / ACCEPTABILITY OF PRINTED BOARDS, CLASS 2, CURRENT REVISION.
- VIA SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003/- .010$.
HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003$.
- REGISTRATION TOLERANCE: ARTWORK $\pm .002$.
ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE $.001$ INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER (SEE DETAIL 'A')
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: $.062 \pm 10\%$
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SMOBC/IMMERSION GOLD: 2 - 5 μ IN OVER 118-236 μ IN NICKEL PLATING.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT)
COLOR = RED.
- SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE $\pm .005$.
INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED $.007$ INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 15MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED $\pm 10\%$.
- ALL OUTER LAYERS USING A 7MIL TRACE WIDTH AND 5MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL $\pm 10\%$.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 6MIL.
MINIMUM COPPER CONDUCTOR SPACING IS: 5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY, MAX REFLOW OF 260 DEGREES C (6 PASSES).

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	10.0	PLATED	969
*	12.0	PLATED	35
•	13.0	PLATED	20
*	38.0	PLATED	110
•	40.0	PLATED	9
◁	40.0	PLATED	6
H	63.0	PLATED	6
Y	125.0	PLATED	4
◁	39.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES \pm .XX \pm .01 \pm .XXX \pm .005 \pm .	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING ADS41XX CAPE TIDA-00942	
DRAWN JY SMITH	05-25-16	SIZE		
MATERIAL	ENG N GILL	05-25-16	DRAWING NO.	REV.
SEE NOTE 5				E1
FINISH	SEE NOTE 7, 8, 9		SCALE	SHEET 1 OF 1
DO NOT SCALE DRAWING		NONE		

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